

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Number : 10/553,470 Confirmation No.: 8935
: National Phase of International App'l. No. PCT/DE2004/000801
Applicant Ralf LERNER
Filed : May 19, 2006
Title : MONITORING THE REDUCTION OF THICKNESS AS
MATERIAL IS REMOVED FROM A WAFER COMPOSITE AND
TEST STRUCTURE FOR MONITORING REMOVAL OF
MATERIAL
TC/Art Unit : 2818
Examiner: : Lopez Esquerria, Andres
Docket No. : 60291.000041
Customer No. : 21967

MAIL STOP AMENDMENTS
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO FINAL OFFICE ACTION UNDER 37 C.F.R. § 1.116

Sir:

AMENDMENT

Amendments to the Claims appear in the Listing of Claims beginning on page 2 of this paper.

Remarks appear on page 7 of this paper.